	Material Compo © Copyright 2005. IP © International and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier	r Information														
Company name* Company unique ID					ι	Unique ID Authority					Response Date*				
nsemi												2024-05-	-10		
Contact N	ame		Title - Contac	et]	Phone - Contact*				Email - Contact*					
Product-H	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Repres	Fitle - Representative Phot			Phone - Repr	ne - Representative*			Email - Representative*				
Product-H	Env-Stewards		Product Envi	ro Compliance		NA Product-Env-Stewards@onsemi.com					m				
	Requester Item Number Mfr Item		Number	Mfr Item Name			Effective Date Version Manufacturing Site Weight*		UOM	Unit Type					
		AR0134CSSM00SUE 1.2 MP 1/3 GS CIS A0-DPBR1		S		2024-05-10		,	TWU		1	191.2	mg	Each	
Ianufa	cturing Proccess Informati	ion													
Terminal Plating / Grid Array Material Terminal Base Alloy J-S			-STD-020 MSL	Rating	Peak Pro	cess Bo	ody Temperatu	re Max 7	Time at Peak	Temperat	ure Num	ber of Reflow Cyc	les		
	SnAgCu	С	U Alloy	4	ļ		260		С	30		secon	ds 3		
omments															
or more i	information regarding material c	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	29.5	mg		Misc.	proprietary data		0.1121	mg
			Supplier	Silicon (Si)	7440-21-3		29.0958	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2921	mg
Die Attach	1.8	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.675	mg
			Supplier	Ethylene Glycol	107-21-1		0.018	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.054	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.378	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.675	mg
Imaging Lens	17.4	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.9158	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		0.9158	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		0.9158	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.0917	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.9158	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		0.9158	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		12.7295	mg
Lid Attach	1.46	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.657	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.292	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.1825	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0073	mg
			Supplier	Curative	Proprietary Data		0.0292	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.292	mg
Iold Compound-Black	65.83	mg		Phenolic Resin	proprietary data		9.8745	mg
			Supplier	Oxirane	39817-09-9		9.8745	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.9749	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6583	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		42.1312	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.3166	mg
older Ball	35.81	mg	Supplier	Silver (Ag)	7440-22-4		1.0743	mg
			Supplier	Tin (Sn)	7440-31-5		34.5567	mg
			Supplier	Copper (Cu)	7440-50-8		0.179	mg
Substrate and Solder Mask	39.07	mg	Supplier	Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane	105391-33-1		0.4376	mg

			Supplier	Fiber Glass (SiO2)	65997-17-3	5.0635	mg
			Supplier	Zinc (Zn)	7440-66-6	0.0586	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	0.9103	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.4376	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.2266	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0039	mg
			Supplier	Acetophenone Derivative	Proprietary Data	1.3635	mg
			Supplier	Carbon Black (C)	1333-86-4	0.2266	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2266	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	4.6884	mg
			В	Nickel (Ni)	7440-02-0	0.5509	mg
			Supplier	Gold (Au)	7440-57-5	0.0195	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	2.731	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.4376	mg
			Supplier	Copper (Cu)	7440-50-8	14.6356	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	7.0521	mg
Wire Bond - Au	0.33	mg	Supplier	Gold (Au)	7440-57-5	0.33	mg